## **MA22D28**

## Silicon epitaxial planar type

#### For high speed switching

#### ■ Features

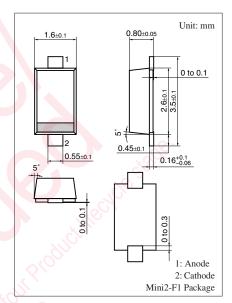
- Forward current  $I_{F(AV)} = 1.5$  A rectification is possible
- ullet Low forward voltage  $V_F$

### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	30	V
Repetitive peak reverse voltage	V <sub>RRM</sub>	30	V
Forward current (Average) *1	I <sub>F(AV)</sub>	1.5	A
Non-repetitive peak forward surge current *2	I <sub>FSM</sub>	30	A
Junction temperature	T <sub>j</sub>	150	°C
Storage temperature	$T_{stg}$	-55 to +150	°C

Note) \*1: Mounted on a alumina PC board

\*2: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

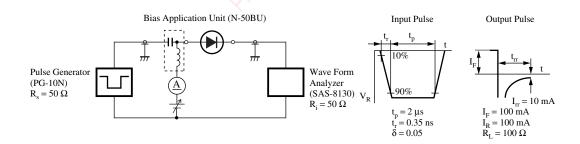


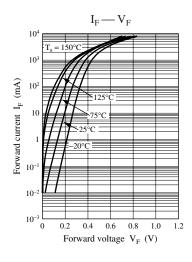
Marking Symbol: 3Z

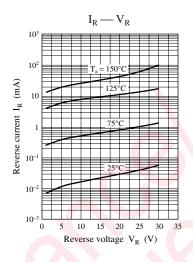
## ■ Electrical Characteristics $T_a = 25$ °C $\pm 3$ °C

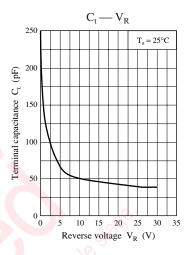
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	$V_{F1}$	$I_{\rm F} = 0.5 \; {\rm A}$	5 15	0.34	0.38	V
	$V_{F2}$	$I_F = 1.0 \text{ A}$		0.38	0.42	
	V <sub>F3</sub>	I <sub>F</sub> = 1.5 A	200	0.42	0.46	
Reverse current	$I_R$	$V_R = 30 \text{ V}$			100	μΑ
Terminal capacitance	C <sub>t</sub>	$V_R = 10 \text{ V}, f = 1 \text{ MHz}$	6	50		pF
Reverse recovery time *	t <sub>rr</sub>	$I_F = I_R = 100 \text{ mA}$		13		ns
, C	9	$I_{rr} = 10 \text{ mA}$ , $R_L = 100 \Omega$				

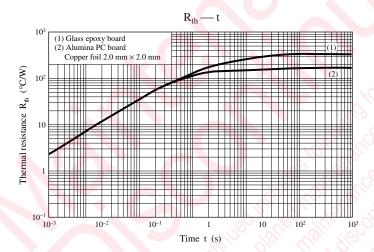
- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
  - 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
  - 3. \*: t<sub>rr</sub> measuring instrument











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